

Notes:

1.Material:

Housing: LCP 30%GF, UL94V-0, Black

Contact : Phosphor Bronze, T=0.15mm

Shell: SUS304-H, T=0.15mm

2.Plating:

Contact:

Contact Area: 3U" GOLD PLATED

Solder Area: G/F Gold

Underplating: Ni overall 50u" Min.

Shell:

Solder Area: G/F Gold

Underplating: Ni overall 50u"

3.Mechanical:

Life cycles: 5000.

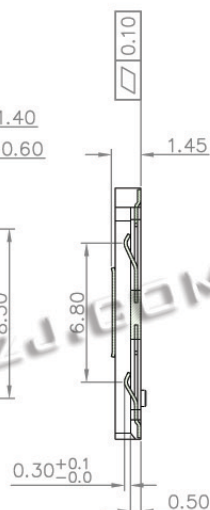
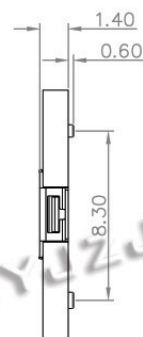
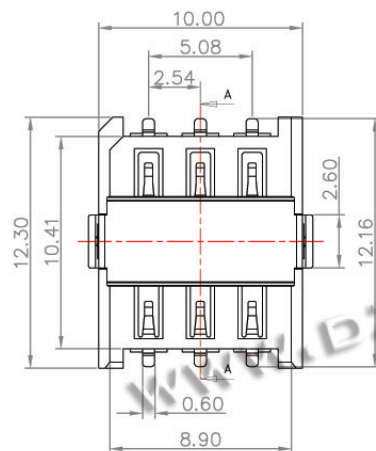
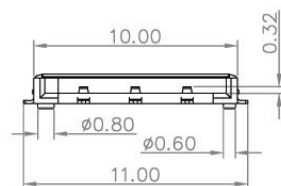
4.Electrical:

Voltage Rating: 30V AC RMS

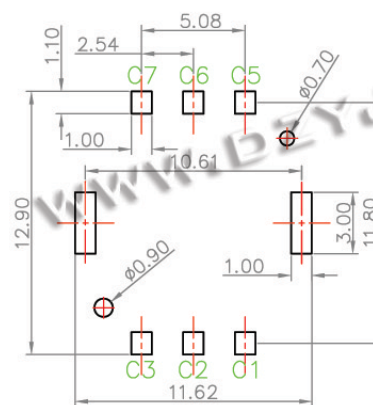
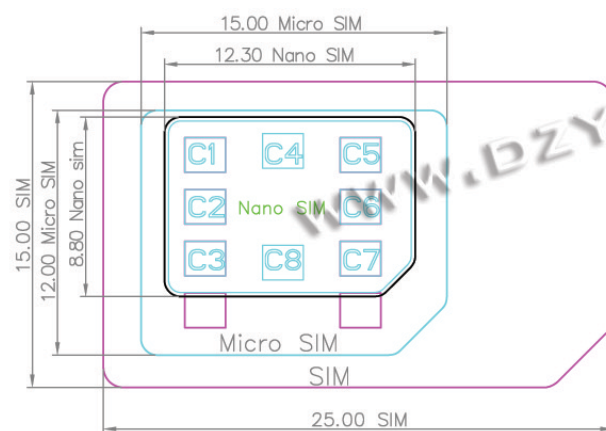
Current Rating: 0.5A AC RMS Max

Operating Temperature: -20? to +80?

Dielectric Withstanding Voltage: 100V AC (60Sec Min)

Insulation Resistance: 100M Ω MinContact Resistance: 30m Ω Max

SECTION: A-A

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ?05Nano SIM Card
REFERENCE DATA

C1 --> VCC
C2 --> RST
C3 --> CLK
C5 --> GND
C6 --> VPP
C7 --> I/O



DESCRIPTION OF PLATING ON TERMINALS

NO.	EXPLAIN	NO.	EXPLAIN
0	GOLD FLASH	3	GOLD 15u"
1	GOLD 5u"	4	GOLD 20u"
2	GOLD 10u"	6	GOLD 30u"



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: NANO SIM 6P 1.45H
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC108-SIM06-145
	APPROVED BY: 邱国夷	DATE : 2014-02-23	DRAW NO: HYC-SIM16060611
SCALE:1:1 SIZE: A4			SHEET NO. 1 OF 1